

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. (Currently Amended) A lead frame for packaging a semiconductor chip, the lead frame comprising:
a frame-shaped land;
~~a die pad for mounting the semiconductor chip;~~
a semiconductor chip mounted to the die pad;
first to fourth support portions formed in four corners of the land and supporting the die pad so that the die pad is located inside the land; and
first to fourth groups of lead members having first ends and second ends that are opposite to the first ends, the first ends being fixed to the land, and the second ends being parallel in each group and connected to the semiconductor chip with a wire;
wherein the lead frame can accommodate semiconductor chips of various different sizes.

2. (Original) A lead frame according to Claim 1, wherein the first to fourth groups of lead members are formed in first to fourth trapezoidal areas, the shorter bases of which face a center of the land and the longer bases of which face sides of the land, and the second ends of the first to fourth groups of lead members are along the shorter bases of the first to fourth trapezoidal areas.

3. (Currently Amended) A method for manufacturing a semiconductor device including a lead frame having a frame-shaped land; a die pad; ~~a for mounting the~~ semiconductor chip mounted to the die pad; first to fourth support portions formed in four corners of the land and supporting the die pad so that the die pad is located inside the land; and first to fourth groups of lead members having first ends and second ends that are opposite to the first ends, the first ends being fixed to the land, and the second ends being parallel in each group and connected to the semiconductor chip with a wire, the method comprising the steps of:

- (a) cutting the first to fourth groups of lead members according to the size of the semiconductor chip to be packaged;
- (b) mounting the semiconductor chip on the die pad;
- (c) bonding the first to fourth groups of lead members and the semiconductor chip with a plurality of wires;
- (d) fitting terminals to the land, for connecting the first to fourth groups of lead members to an external circuit; and
- (e) encapsulating the lead frame and the semiconductor chip;
wherein the lead frame can accommodate semiconductor chips of various different sizes.

4. – 6. (Cancelled)